20 HOW TO REPLACE FLAT PACKAGE IC

20.1. Preparation

- SOLDER

  Sparkle Solder 115A-1, 115B-1 or Almit Solder KR-19, KR-19RMA

- Soldering iron

  Recommended power consumption will be between 30 W to 40 W.

  Temperature of Copper Rod 662 ± 50°F (350 ± 10°C)

  (An expert may handle between 60 W to 80 W iron, but beginner might damage foil by overheating.)

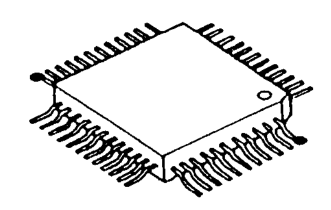
- Flux

  HI115 Specific gravity 0.863.

  (Original flux will be replaced daily.)

20.2. Procedure

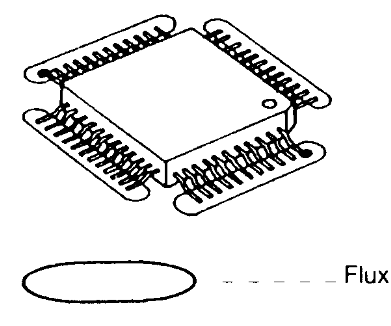
1. Temporary fix FLAT PACKAGE IC by soldering on two marked 2 pins.



● - - - - - - -Temporary soldering point.

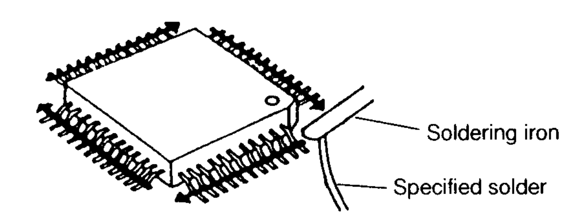
*Most important matter is accurate setting of IC to the corresponding soldering foil.

2. Apply flux for all pins of FLAT PACKAGE IC.



(oval) - - - - - - Flux

3. Solder employing specified solder to direction of arrow, as sliding the soldering iron.



20.3. Modification Procedure of Bridge

1. Re-solder slightly on bridged portion.
2. Remove remained solder along pins employing soldering iron as shown in below figure.

